

PolarHT™ HiPerFET IXFR 140N20P

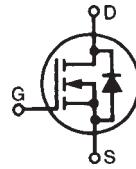
Power MOSFET

ISOPLUS247™

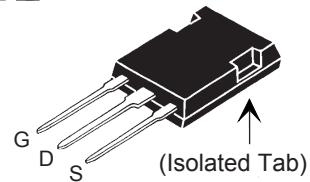
(Electrically Isolated Back Surface)

N-Channel Enhancement Mode
Fast Intrinsic Diode
Avalanche Rated

$V_{DSS} = 200$ V
 $I_{D25} = 90$ A
 $R_{DS(on)} \leq 22$ mΩ
 $t_{rr} \leq 200$ ns



ISOPLUS247 (IXFR)
E153432



G = Gate D = Drain
S = Source

Symbol	Test Conditions	Maximum Ratings		
V_{DSS}	$T_J = 25^\circ C$ to $175^\circ C$	200		V
V_{DGR}	$T_J = 25^\circ C$ to $175^\circ C$; $R_{GS} = 1 M\Omega$	200		V
V_{GS}	Continuous	± 20		V
V_{GSM}	Transient	± 30		V
I_{D25}	$T_c = 25^\circ C$	90		A
$I_{D(RMS)}$	External lead current limit	75		A
I_{DM}	$T_c = 25^\circ C$, pulse width limited by T_{JM}	280		A
I_{AR}	$T_c = 25^\circ C$	60		A
E_{AR}	$T_c = 25^\circ C$	100		mJ
E_{AS}	$T_c = 25^\circ C$	4		J
dv/dt	$I_s \leq I_{DM}$, $di/dt \leq 100$ A/ μ s, $V_{DD} \leq V_{DSS}$, $T_j \leq 150^\circ C$, $R_G = 4 \Omega$	10		V/ns
P_D	$T_c = 25^\circ C$	300		W
T_J		-55 ... +175		°C
T_{JM}		175		°C
T_{stg}		-55 ... +150		°C
T_L	1.6 mm (0.062 in.) from case for 10 s	300		°C
V_{ISOL}	50/60 Hz, RMS, 1 minute	2500		V~
M_d	Terminal torque Mounting torque	1.13/10 Nm/lb.in. 1.13/10 Nm/lb.in.		
Weight		5		g

Symbol	Test Conditions ($T_J = 25^\circ C$, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
BV_{DSS}	$V_{GS} = 0 V$, $I_D = 250 \mu A$	200		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 4 mA$	2.5		V
I_{GSS}	$V_{GS} = \pm 20 V_{DC}$, $V_{DS} = 0$		± 200	nA
I_{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0 V$		25 250	μA
		$T_J = 150^\circ C$		
$R_{DS(on)}$	$V_{GS} = 10 V$, $I_D = 0.5 I_{D25}$ $V_{GS} = 15 V$, $I_D = 140 A$ Pulse test, $t \leq 300 \mu s$, duty cycle $d \leq 2 \%$	17	22	mΩ

Features

- International standard isolated package
- UL recognized package
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
 - easy to drive and to protect
- Fast intrinsic diode

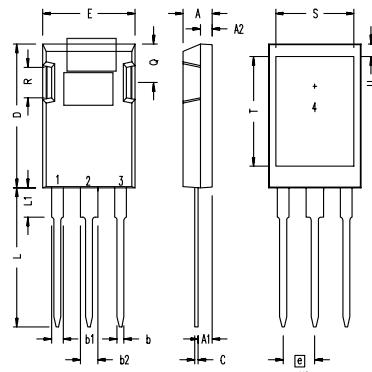
Advantages

- Easy to mount
- Space savings
- High power density

Symbol	Test Conditions	Characteristic Values			
		($T_J = 25^\circ C$, unless otherwise specified)	Min.	Typ.	Max.
g_{fs}	$V_{DS} = 10 V$; $I_D = 0.5 I_{D25}$, pulse test	50	84	S	
C_{iss}		7500		pF	
C_{oss}		1800		pF	
C_{rss}		280		pF	
$t_{d(on)}$		30		ns	
t_r		35		ns	
$t_{d(off)}$	$V_{GS} = 10 V$, $V_{DS} = 0.5 V_{DSS}$, $I_D = 60 A$	150		ns	
t_f	$R_G = 3.3 \Omega$ (External)	90		ns	
$Q_{g(on)}$		240		nC	
Q_{gs}		50		nC	
Q_{gd}		100		nC	
R_{thJC}			0.5	$^\circ C/W$	
R_{thcs}	ISOPLUS247	0.15		$^\circ C/W$	

Source-Drain Diode**Characteristic Values**
($T_J = 25^\circ C$, unless otherwise specified)

Symbol	Test Conditions	Min.	typ.	Max.
I_s	$V_{GS} = 0 V$			90 A
I_{SM}	Repetitive			280 A
V_{SD}	$I_F = I_s$, $V_{GS} = 0 V$, Pulse test, $t \leq 300 \mu s$, duty cycle $d \leq 2\%$			1.5 V
t_{rr}	$I_F = 25 A$, $-di/dt = 100 A/\mu s$			200 ns
Q_{RM}	$V_R = 100 V$, $V_{GS} = 0 V$	0.6		μC
I_{RM}		6		A

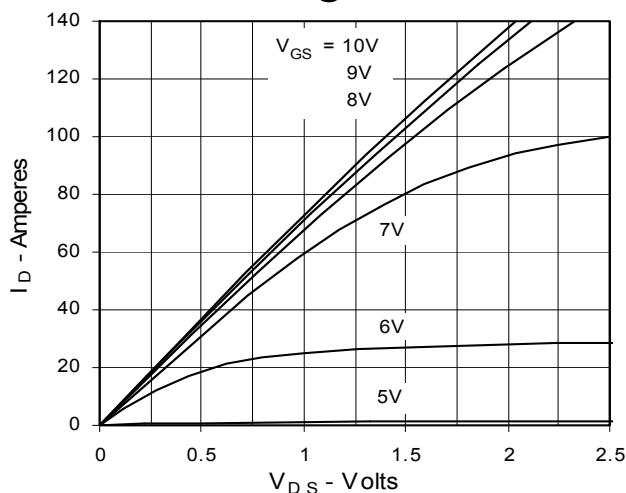
ISOPLUS 247 OUTLINE

Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	4.83	5.21	.190	.205
A ₁	2.29	2.54	.090	.100
A ₂	1.91	2.16	.075	.085
b	1.14	1.40	.045	.055
b ₁	1.91	2.13	.075	.084
b ₂	2.92	3.12	.115	.123
C	0.61	0.80	.024	.031
D	20.80	21.34	.819	.840
E	15.75	16.13	.620	.635
e	5.45	BSC	.215	BSC
L	19.81	20.32	.780	.800
L1	3.81	4.32	.150	.170
Q	5.59	6.20	.220	.244
R	4.32	4.83	.170	.190

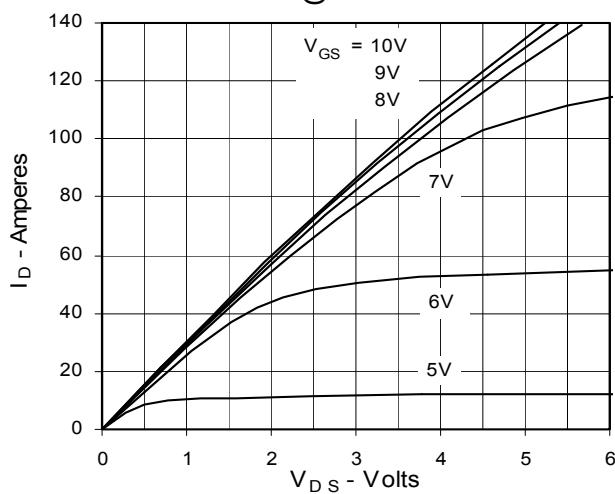
IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 one or more of the following U.S. patents: 4,850,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405B2 6,759,692 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6771478 B2

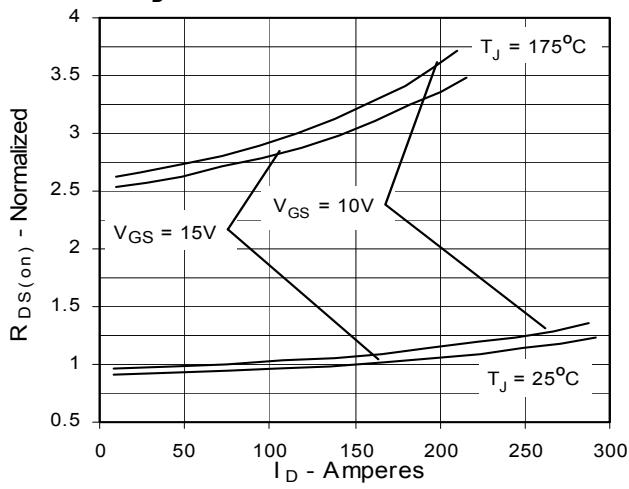
**Fig. 1. Output Characteristics
@ 25°C**



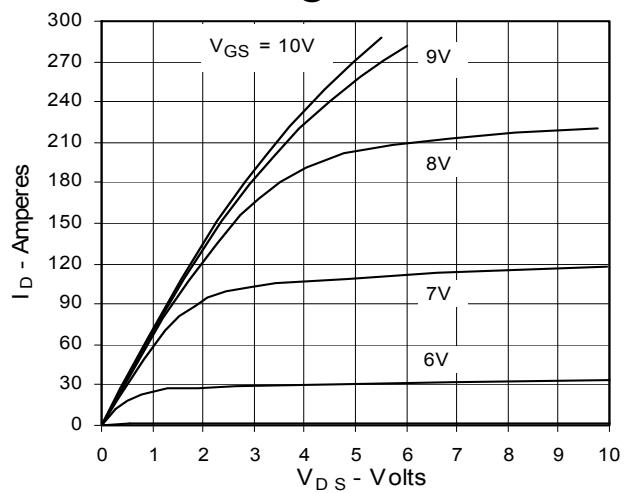
**Fig. 3. Output Characteristics
@ 150°C**



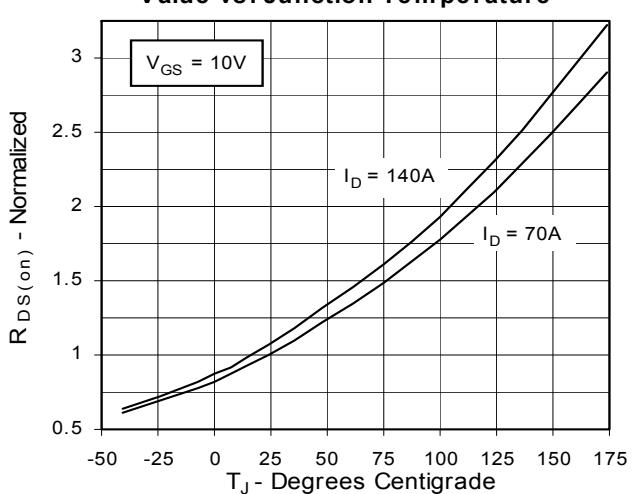
**Fig. 5. $R_{DS(on)}$ Normalized to
 $I_D = 70A$ Value vs. Drain Current**



**Fig. 2. Extended Output Characteristics
@ 25°C**



**Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 70A$
Value vs. Junction Temperature**



**Fig. 6. Drain Current vs. Case
Temperature**

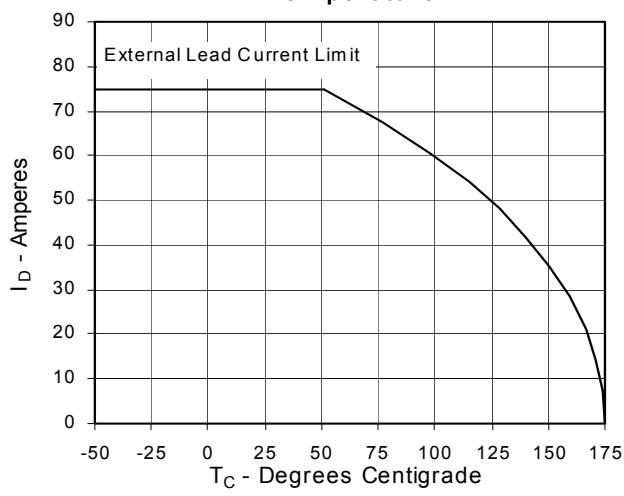


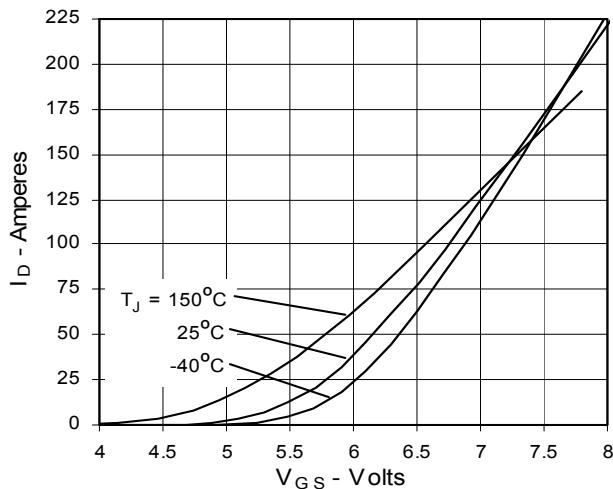
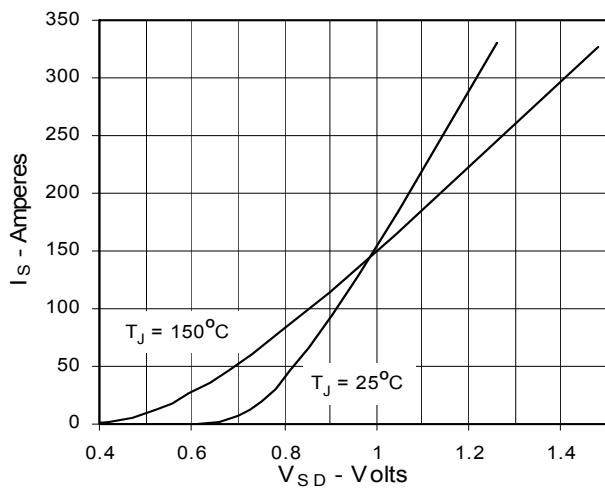
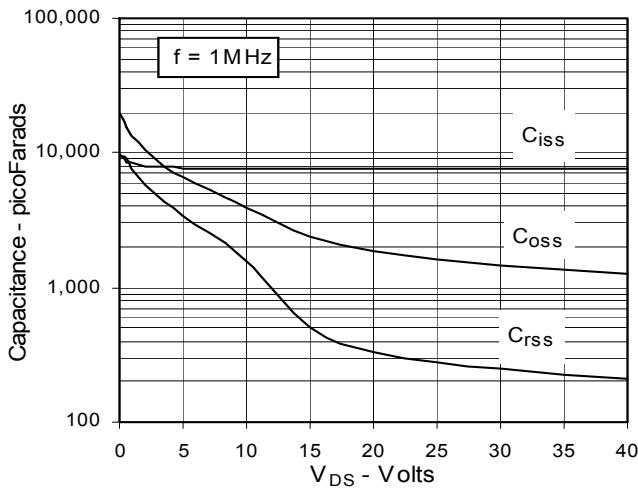
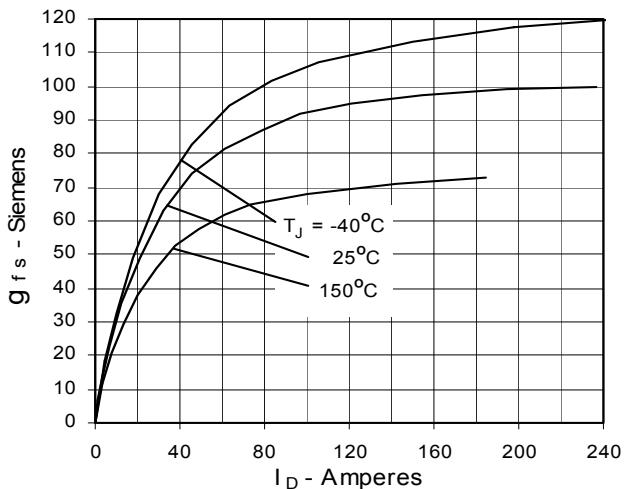
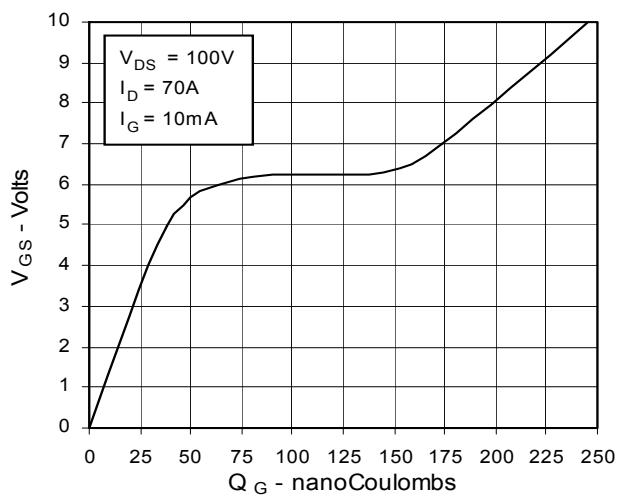
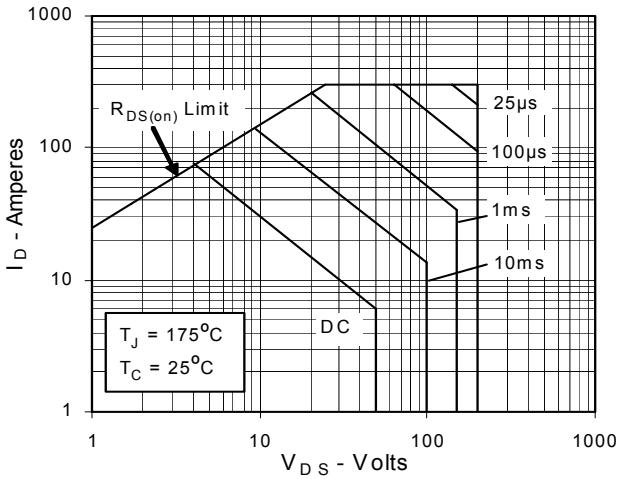
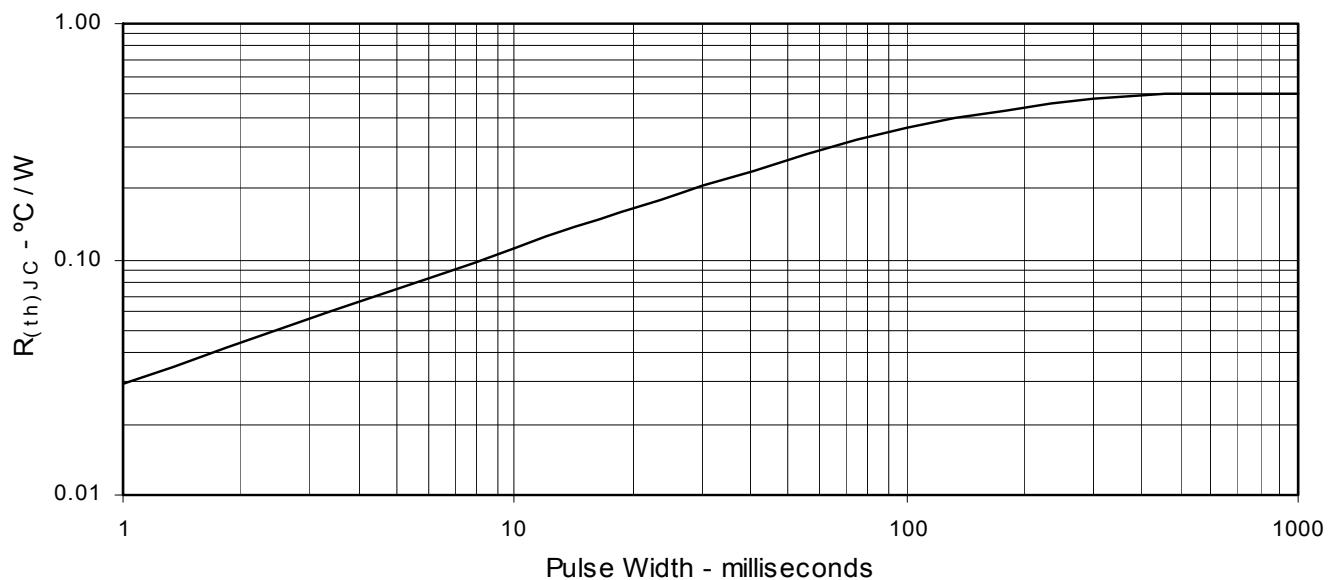
Fig. 7. Input Admittance**Fig. 9. Source Current vs. Source-To-Drain Voltage****Fig. 11. Capacitance****Fig. 8. Transconductance****Fig. 10. Gate Charge****Fig. 12. Forward-Bias Safe Operating Area**

Fig. 13. Maximum Transient Thermal Resistance



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